



**THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application

Title: PROCESS FOR FORMING A DIRECT BUILD-UP LAYER ON AN  
ENCAPSULATED DIE PACKAGES UTILIZING INTERMEDIATE STRUCTURES

Docket No.: 884.791US1  
Filed: September 14, 2000  
Examiner: Unknown  
Customer No.: 21186

Serial No.: 09/661,899  
Due Date: April 7, 2005  
Group Art Unit: Unknown  
Confirmation No.:

Commissioner for Patents  
Attn: MAIL STOP ISSUE FEE  
P.O. Box 1450  
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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
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**CERTIFICATE UNDER 37 CFR 1.8:** The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, Attn – MAIL STOP ISSUE FEE, P.O. Box 1450, Alexandria, VA 22313-1450, on this 7 day of April, 2005.

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